

1.6X1.25mm BI-COLOR SMD CHIP LED LAMP

Part Number: APTB1612LSURKCGKC

Hyper Red Green

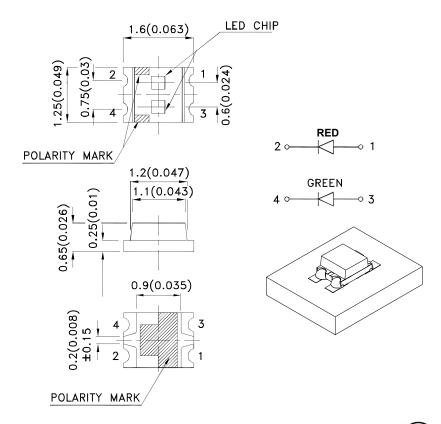
Features

- 1.6mmx1.25mm SMD LED, 0.65mm thickness.
- Bi-color,low power consumption.
- Wide viewing angle.
- Ideal for backlight and indicator.
- Package: 2000pcs / reel.
- Moisture sensitivity level : level 3.
- Low current IF=2mA operating.
- RoHS compliant.

Descriptions

- The Hyper Red source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode.
- The Green source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode.

Package Dimensions



Notes:

- 1. All dimensions are in millimeters (inches).
 2. Tolerance is ±0.2(0.008") unless otherwise noted.
- 3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.

4. The device has a single mounting surface. The device must be mounted according to the specifications.

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Selection Guide

Part No.	Emitting Color (Material)	Lens Type	lv (mcd) [2] @ 2mA		Viewing Angle [1]
			Min.	Тур.	201/2
APTB1612LSURKCGKC	Hyper Red (AlGaInP)		10	20	- 120°
		Water Clear	*4	*9	
	Green (AlGalnP)		1.2	3	
			*1.2	*3	

- 1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
- Luminous intensity / luminous Flux: +/-15%.
 Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Emitting Color	Min.	Тур.	Max.	Units	Test Conditions	
λpeak	Peak Wavelength	Hyper Red Green		645 574		nm	IF=2mA	
λD [1]	Dominant Wavelength	Hyper Red Green		630 570		nm	IF=2mA	
Δλ1/2	Spectral Line Half-width	Hyper Red Green		28 20		nm	IF=2mA	
С	Capacitance	Hyper Red Green		35 15		pF	VF=0V;f=1MHz	
VF [2]	Forward Voltage	Hyper Red Green	1.5 1.5	1.75 1.9	2.1 2.1	V	IF=2mA	
lR	Reverse Current	Hyper Red Green			10 10	uA	V _R = 5V	

Notes:

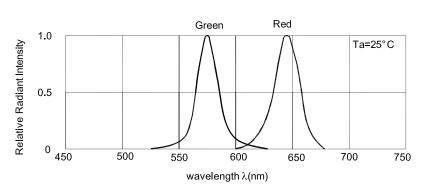
- 1. Wavelength: +/-1nm.
- 2. Forward Voltage: +/-0.1V.
- 3. Wavelength value is traceable to the CIE127-2007 compliant national standards.
- 4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

Absolute Maximum Ratings at TA=25°C

Parameter	Hyper Red	Green	Units			
Power dissipation	63	63	mW			
DC Forward Current	30	30	mA			
Peak Forward Current [1]	185	150	mA			
Reverse Voltage		V				
Operating Temperature	-40°C To +85°C					
Storage Temperature	-40°C To +85°C					

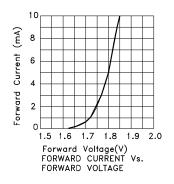
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

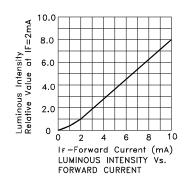
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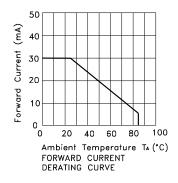


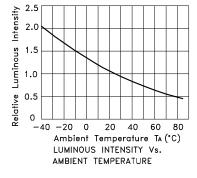
Relative Intensity Vs. Wavelength

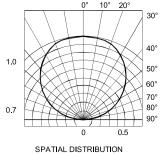
APTB1612LSURKCGKC Hyper Red







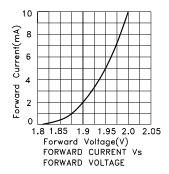


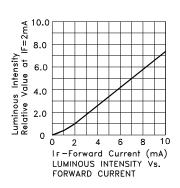


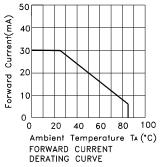
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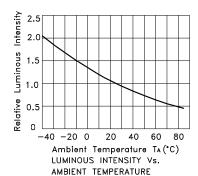
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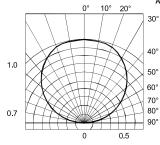
Green











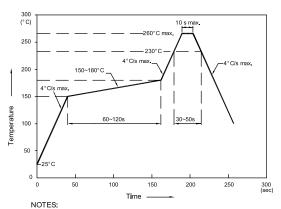
SPATIAL DISTRIBUTION

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Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



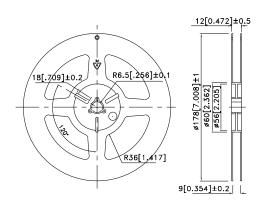
- 1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
- 2.Don't cause stress to the epoxy resin while it is exposed to high temperature
- to high temperature.
 3.Number of reflow process shall be 2 times or less.

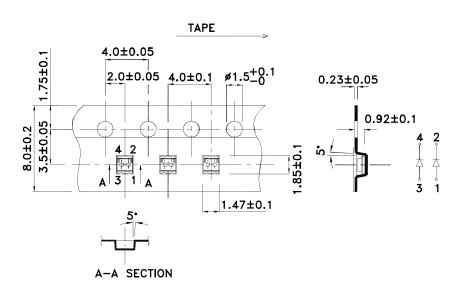
Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)

0.8

Tape Dimensions (Units : mm)

Reel Dimension

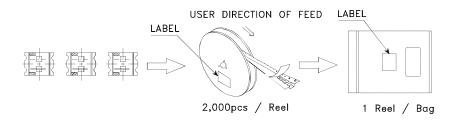


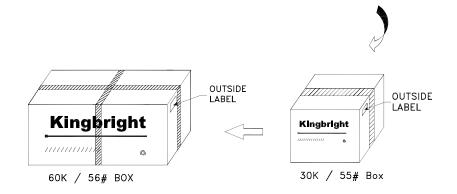


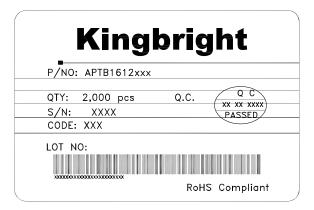
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PACKING & LABEL SPECIFICATIONS

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